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Part Number: [73944-7017](#)
Status: **Active**
Overview: [HDM® Backplane Connector System](#)
Description: HDM® Board-to-Board Backplane Header, Vertical, SMC, Solder Tail, Guide Pin Option, 144 Circuits

Documents:
[3D Model](#) [Product Specification PS-73670-9999 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

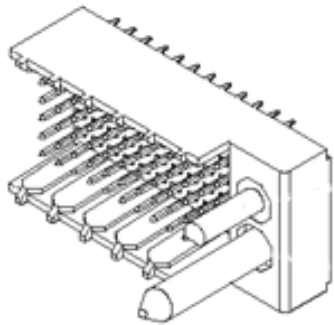
CSA LR19980
UL E29179

General

Product Family Backplane Connectors
Series [73944](#)
Application Backplane
Component Type PCB Header
Overview [HDM® Backplane Connector System](#)
Product Name HDM®
Style N/A
UPC 800755031096

Physical

Circuits (Loaded) 144
Circuits (maximum) 144
Color - Resin Black, Natural
Durability (mating cycles max) 250
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part Yes
Keying to Mating Part Yes
Material - Metal Phosphor Bronze, Stainless Steel
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
Net Weight 8.594/g
Number of Columns 24
Number of Pairs Open Pin Field
Number of Rows 6
Orientation Vertical
PC Tail Length 3.50mm
PCB Locator Yes
PCB Retention None
PCB Thickness - Recommended 2.50mm
Packaging Type Tube
Pitch - Mating Interface 2.00mm
Pitch - Termination Interface 2.00mm
Plating min - Mating 0.762µm
Plating min - Termination 2.540µm
Polarized to PCB No
Stackable No
Surface Mount Compatible (SMC) No
Temperature Range - Operating -55°C to +105°C
Termination Interface: Style Through Hole



Series

image - Reference only

EU RoHS
ELV and RoHS
Compliant
REACH SVHC
Contains SVHC: No
Low-Halogen Status
Low-Halogen

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[73944Series](#)

Mates With
73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Application Tooling FAQ	
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.	
Global	
Description	Product #
Backplane Insertion	0621001400
Signal Contact Tool	
Backplane Insertion	0622005703
Head for 144 Circuits	
Extraction Tool	0621001000

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Shielded	No
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	40
Lead-free Process Capability	SMC & Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	3
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Product Specification	PS-73670-9999
Sales Drawing	SD-73944-001

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